



Press release

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Henkel to Debut Breakthrough Technologies at Semicon West 2006

Leading packaging firms who visit the Henkel booth at Semicon West 2006 in San Francisco, California, will see several innovative materials technologies that are certain to deliver new levels of cost and production efficiencies for modern packaging processes.

The first product, Hysol® QMI536NB is a revolutionary new die attach material developed for stacked die applications that require extremely low stress and robust mechanical properties. The material is qualified for use in lead-free environments and provides an alternative to film die attach. Hysol QMI536NB delivers new levels of supply chain efficiency, enabling users to qualify a single material for stacked die packages. Traditionally, different die attach materials are used for the various layers of a stacked package so as to avoid damage to the die passivation of the first die. However, through its unique protective and low-bleed formulation, Hysol QMI536NB can be used for both mother and daughter die, simplifying production processes and lowering costs.

Also being unveiled at the Semicon West event is Henkel's patent-pending Accelerated Cooling (AC) process for flip-chip manufacturing. The process is used in conjunction with Henkel's non-conductive paste (NCP) underfill encapsulants, Hysol FP5000 and Hysol FP5001, and enables rapid cooling of the device prior to any excessive heat exposure, thus reducing warpage and voids while improving cycle time by nearly 50% over that of previous thermal compression processes. This manufacturing improvement comes at a time when packaging companies are migrating away from wire-bonded, face up assemblies toward flip-chip packages to gain footprint and performance efficiencies.

High-performance, compatible material set development is one of the hallmarks of the Henkel product philosophy. And, there is no better venue than Semicon West to introduce yet another process-optimized material set to the marketplace. Henkel's Hysol QMI529LS and Hysol GR828A material set is a die attach and mold compound combination designed specifically for thin and ultra-thin surface mount device (SMD) applications. Both materials are optimized for use in lead-free environments and

provide the thin, yet reliable, materials characteristics required for use in today's low-profile consumer electronics products.

To find out more about these latest Henkel materials technologies or any of the company's high-performance products, visit Henkel in booth #8411 at Semicon West 2006, July 11 through 13 at San Francisco's Moscone Center or log onto www.henkelelectronics.com.

About the electronics group of Henkel

Henkel is one of the world's leading and most progressive providers of qualified, compatible material sets for semiconductor packaging, board level assembly and advanced soldering solutions. Through its Hysol, Loctite and Multicore brands, and its global customer support infrastructure, the electronics group of Henkel delivers world-class materials products, process expertise and total solutions across the board to enable tomorrow's electronic industry.

Henkel, a Fortune Global 500 company, operates in three strategic business areas: Home Care; Personal care; and Adhesives, Sealants and Surface Treatments, which serves the transportation, electronics, aerospace, metal, durable goods, consumer goods, maintenance and repair and packaging industries, and offers a broad range of products for the craftsman and consumer. With brands and technologies, Henkel makes people's lives easier, better, and more beautiful. 50,000 employees work for Henkel worldwide. People in 125 countries around the world trust in brands and technologies from Henkel – "A Brand like a Friend".

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